Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	RX
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, SCI, SPI, USB
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	30
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 10x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f51111adfl-3a

1.4 Pin Functions

Table 1.4 lists the pin functions.

Table 1.4 Pin Functions (1/3)

Classifications	Pin Name	I/O	Description
Power supply	VCC	Input	Power supply pin. Connect it to the system power supply.
	VCL	—	Connect this pin to the VSS pin via the 4.7 µF smoothing capacitor used to stabilize the internal power supply. Place the capacitor close to the pin.
	VSS	Input	Ground pin. Connect it to the system power supply (0 V).
	VCC_USB	Input	Power supply pin for USB. Connect this pin to VCC.
	VSS_USB	Input	Ground pin for USB. Connect this pin to VSS.
Analog power supply	AVCC0	Input	Analog voltage supply pin for the 12-bit A/D converter. Connect this pin to VCC when not using the 12-bit A/D converter.
	AVSS0	Input	Analog ground pin for the 12-bit A/D converter. Connect this pin to VSS when not using the 12-bit A/D converter.
	VREFH0	Input	Analog reference voltage supply pin for the 12-bit A/D converter. Connect this pin to VCC when not using the 12-bit A/D converter.
	VREFL0	Input	Analog reference ground pin for the 12-bit A/D converter. Connect this pin to VSS when not using the 12-bit A/D converter.
Clock	XTAL	Output/ Input *1	Pins for connecting a crystal. An external clock can be input through the XTAL pin.
	EXTAL	Input	
	XCIN	Input	Input/output pins for the sub-clock oscillator. Connect a crystal between XCIN and XCOUT.
	XCOUT	Output	
	CLKOUT	Output	Clock output pin.
Operating mode control	MD	Input	Pin for setting the operating mode. The signal levels on this pin must not be changed during operation.
	UB#	Input	Pin used for boot mode (USB interface).
	UPSEL	Input	Pin used for boot mode (USB interface).
System control	RES#	Input	Reset pin. This MCU enters the reset state when this signal goes low.
CAC	CACREF	Input	Input pin for the clock frequency accuracy measurement circuit.
On-chip emulator	FINED	I/O	FINE interface pin.
LVD	CMPA2	Input	Detection target voltage pin for voltage detection 2
Interrupts	NMI	Input	Non-maskable interrupt request pin.
	IRQ0 to IRQ7	Input	Interrupt request pins.
Multi-function timer pulse unit 2	MTIOC0A, MTIOC0B MTIOC0C, MTIOC0D	I/O	The TGRA0 to TGRD0 input capture input/output compare output/PWM output pins.
	MTIOC1A, MTIOC1B	I/O	The TGRA1 and TGRB1 input capture input/output compare output/PWM output pins.
	MTIOC2A, MTIOC2B	I/O	The TGRA2 and TGRB2 input capture input/output compare output/PWM output pins.
	MTIOC3A, MTIOC3B MTIOC3C, MTIOC3D	I/O	The TGRA3 to TGRD3 input capture input/output compare output/PWM output pins.
	MTIOC4A, MTIOC4B MTIOC4C, MTIOC4D	I/O	The TGRA4 to TGRD4 input capture input/output compare output/PWM output pins.
	MTIC5U, MTIC5V, MTIC5W	Input	The TGRU5, TGRV5, and TGRW5 input capture input/external pulse input pins.
	MTCLKA, MTCLKB, MTCLKC, MTCLKD	Input	Input pins for the external clock.
Port output enable 2	POE0# to POE3#, POE8#	Input	Input pins for request signals to place the MTU pins in the high impedance state.

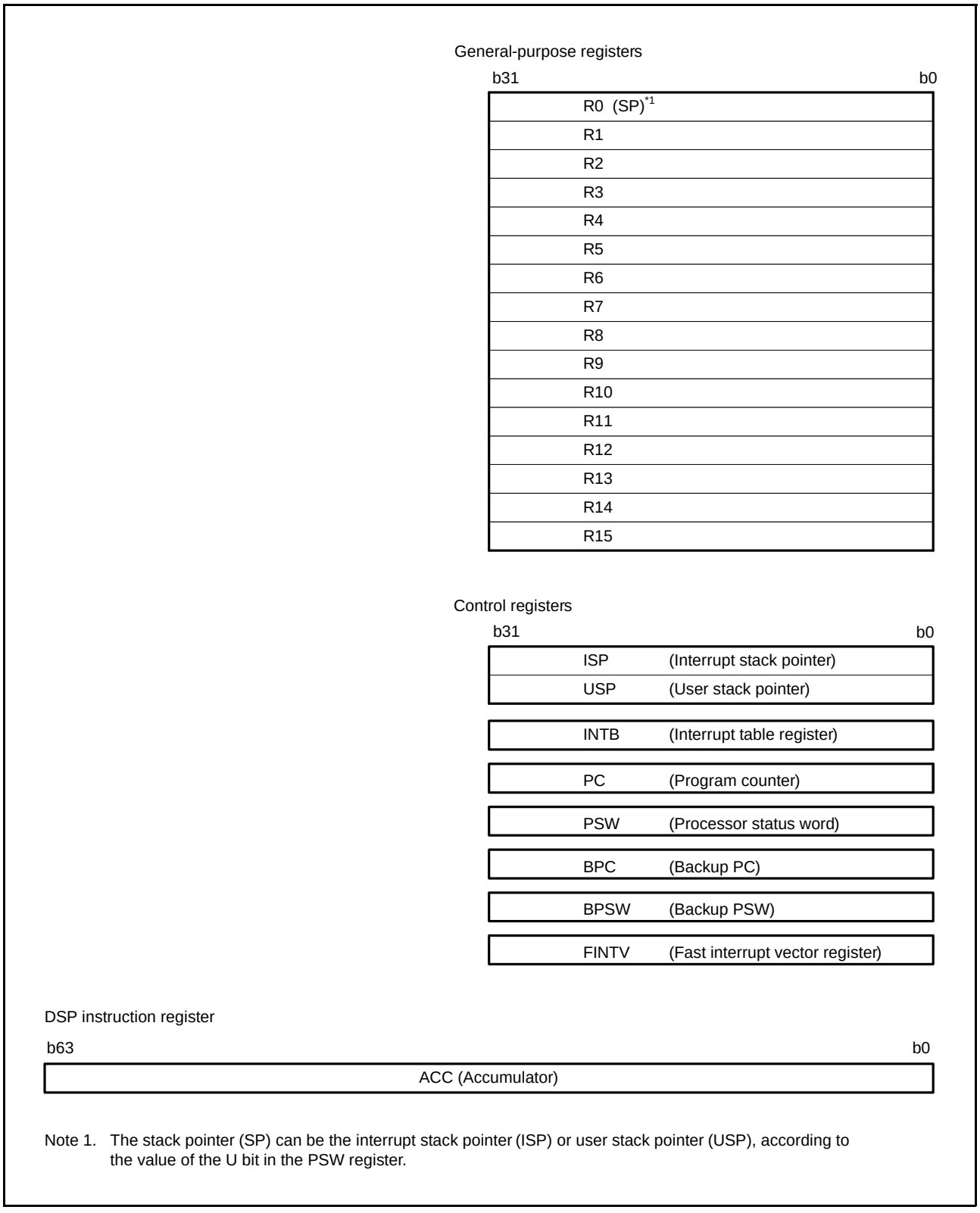
Table 1.7 List of Pins and Pin Functions (48-Pin LFQFP/HWQFN) (2/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, POE, RTC)	Communication (SCIe, SCIf, RSPI, RIIC, USB)	Others
39		PE0	MTIOC2A/POE3#	SCK12	IRQ0/AN008
40		PE7			IRQ7/AN015
41		P46*2			AN006
42		P42*2			AN002
43		P41*2			AN001
44	VREFL0	PJ7*2			
45		P40*2			AN000
46	VREFH0	PJ6*2			
47	AVSS0				
48	AVCC0				

Note 1. Not 5 V tolerant.
Note 2. The power source of the I/O buffer for these pins is AVCC0.

2. CPU

Figure 2.1 shows the register set of the CPU.



Note 1. The stack pointer (SP) can be the interrupt stack pointer (ISP) or user stack pointer (USP), according to the value of the U bit in the PSW register.

Figure 2.1 Register Set of the CPU

4. I/O Registers

This section provides information on the on-chip I/O register addresses and bit configuration. The information is given as shown below. Notes on writing to I/O registers are also given below.

(1) I/O register addresses (address order)

- Registers are listed from the lower allocation addresses.
- Registers are classified according to module symbols.
- Numbers of cycles for access indicate numbers of cycles of the given base clock.
- Among the internal I/O register area, addresses not listed in the list of registers are reserved. Reserved addresses must not be accessed. Do not access these addresses; otherwise, the operation when accessing these bits and subsequent operations cannot be guaranteed.

(2) Notes on writing to I/O registers

While writing to an I/O register, the CPU starts executing subsequent instructions before the I/O register write access is completed. This may cause the subsequent instructions to be executed before the write value is reflected in the operation. The examples below show how subsequent instructions must be executed after a write access to an I/O register is completed.

[Examples of cases requiring special care]

- The subsequent instruction must be executed while an interrupt request is disabled with the IENj bit in IERn of the ICU (interrupt request enable bit) set to 0.
- A WAIT instruction is executed immediately after the preprocessing for causing a transition to the low power consumption state.

In the above cases, after writing to an I/O register, wait until the write operation is completed using the following procedure and then execute the subsequent instruction.

(a) Write to an I/O register.
(b) Read the value in the I/O register and write it to a general register.
(c) Execute the operation using the value read.
(d) Execute the subsequent instruction.

Example of instructions

- Byte-size I/O registers

```
MOV.L  #SFR_ADDR, R1
MOV.B  #SFR_DATA, [R1]
CMP    [R1].UB, R1
;; Next process
```

- Word-size I/O registers

```
MOV.L  #SFR_ADDR, R1
MOV.W  #SFR_DATA, [R1]
CMP    [R1].W, R1
;; Next process
```

Table 4.1 List of I/O Registers (Address Order) (2/16)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 7026h	ICU	Interrupt Request Register 038	IR038	8	8	2 ICLK
0008 702Ch	ICU	Interrupt Request Register 044	IR044	8	8	2 ICLK
0008 702Dh	ICU	Interrupt Request Register 045	IR045	8	8	2 ICLK
0008 702Eh	ICU	Interrupt Request Register 046	IR046	8	8	2 ICLK
0008 702Fh	ICU	Interrupt Request Register 047	IR047	8	8	2 ICLK
0008 7039h	ICU	Interrupt Request Register 057	IR057	8	8	2 ICLK
0008 703Fh	ICU	Interrupt Request Register 063	IR063	8	8	2 ICLK
0008 7040h	ICU	Interrupt Request Register 064	IR064	8	8	2 ICLK
0008 7041h	ICU	Interrupt Request Register 065	IR065	8	8	2 ICLK
0008 7042h	ICU	Interrupt Request Register 066	IR066	8	8	2 ICLK
0008 7043h	ICU	Interrupt Request Register 067	IR067	8	8	2 ICLK
0008 7044h	ICU	Interrupt Request Register 068	IR068	8	8	2 ICLK
0008 7045h	ICU	Interrupt Request Register 069	IR069	8	8	2 ICLK
0008 7046h	ICU	Interrupt Request Register 070	IR070	8	8	2 ICLK
0008 7047h	ICU	Interrupt Request Register 071	IR071	8	8	2 ICLK
0008 7058h	ICU	Interrupt Request Register 088	IR088	8	8	2 ICLK
0008 7059h	ICU	Interrupt Request Register 089	IR089	8	8	2 ICLK
0008 705Ah	ICU	Interrupt Request Register 090	IR090	8	8	2 ICLK
0008 705Ch	ICU	Interrupt Request Register 092	IR092	8	8	2 ICLK
0008 705Dh	ICU	Interrupt Request Register 093	IR093	8	8	2 ICLK
0008 7066h	ICU	Interrupt Request Register 102	IR102	8	8	2 ICLK
0008 7067h	ICU	Interrupt Request Register 103	IR103	8	8	2 ICLK
0008 706Ah	ICU	Interrupt Request Register 106	IR106	8	8	2 ICLK
0008 7072h	ICU	Interrupt Request Register 114	IR114	8	8	2 ICLK
0008 7073h	ICU	Interrupt Request Register 115	IR115	8	8	2 ICLK
0008 7074h	ICU	Interrupt Request Register 116	IR116	8	8	2 ICLK
0008 7075h	ICU	Interrupt Request Register 117	IR117	8	8	2 ICLK
0008 7076h	ICU	Interrupt Request Register 118	IR118	8	8	2 ICLK
0008 7077h	ICU	Interrupt Request Register 119	IR119	8	8	2 ICLK
0008 7078h	ICU	Interrupt Request Register 120	IR120	8	8	2 ICLK
0008 7079h	ICU	Interrupt Request Register 121	IR121	8	8	2 ICLK
0008 707Ah	ICU	Interrupt Request Register 122	IR122	8	8	2 ICLK
0008 707Bh	ICU	Interrupt Request Register 123	IR123	8	8	2 ICLK
0008 707Ch	ICU	Interrupt Request Register 124	IR124	8	8	2 ICLK
0008 707Dh	ICU	Interrupt Request Register 125	IR125	8	8	2 ICLK
0008 707Eh	ICU	Interrupt Request Register 126	IR126	8	8	2 ICLK
0008 707Fh	ICU	Interrupt Request Register 127	IR127	8	8	2 ICLK
0008 7080h	ICU	Interrupt Request Register 128	IR128	8	8	2 ICLK
0008 7081h	ICU	Interrupt Request Register 129	IR129	8	8	2 ICLK
0008 7082h	ICU	Interrupt Request Register 130	IR130	8	8	2 ICLK
0008 7083h	ICU	Interrupt Request Register 131	IR131	8	8	2 ICLK
0008 7084h	ICU	Interrupt Request Register 132	IR132	8	8	2 ICLK
0008 7085h	ICU	Interrupt Request Register 133	IR133	8	8	2 ICLK
0008 7086h	ICU	Interrupt Request Register 134	IR134	8	8	2 ICLK
0008 7087h	ICU	Interrupt Request Register 135	IR135	8	8	2 ICLK
0008 7088h	ICU	Interrupt Request Register 136	IR136	8	8	2 ICLK
0008 7089h	ICU	Interrupt Request Register 137	IR137	8	8	2 ICLK
0008 708Ah	ICU	Interrupt Request Register 138	IR138	8	8	2 ICLK
0008 708Bh	ICU	Interrupt Request Register 139	IR139	8	8	2 ICLK
0008 708Ch	ICU	Interrupt Request Register 140	IR140	8	8	2 ICLK
0008 708Dh	ICU	Interrupt Request Register 141	IR141	8	8	2 ICLK
0008 70AAh	ICU	Interrupt Request Register 170	IR170	8	8	2 ICLK

Table 4.1 List of I/O Registers (Address Order) (3/16)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 70ABh	ICU	Interrupt Request Register 171	IR171	8	8	2 ICLK
0008 70DAh	ICU	Interrupt Request Register 218	IR218	8	8	2 ICLK
0008 70DBh	ICU	Interrupt Request Register 219	IR219	8	8	2 ICLK
0008 70DCh	ICU	Interrupt Request Register 220	IR220	8	8	2 ICLK
0008 70DDh	ICU	Interrupt Request Register 221	IR221	8	8	2 ICLK
0008 70DEh	ICU	Interrupt Request Register 222	IR222	8	8	2 ICLK
0008 70DFh	ICU	Interrupt Request Register 223	IR223	8	8	2 ICLK
0008 70E0h	ICU	Interrupt Request Register 224	IR224	8	8	2 ICLK
0008 70E1h	ICU	Interrupt Request Register 225	IR225	8	8	2 ICLK
0008 70EEh	ICU	Interrupt Request Register 238	IR238	8	8	2 ICLK
0008 70EFh	ICU	Interrupt Request Register 239	IR239	8	8	2 ICLK
0008 70F0h	ICU	Interrupt Request Register 240	IR240	8	8	2 ICLK
0008 70F1h	ICU	Interrupt Request Register 241	IR241	8	8	2 ICLK
0008 70F2h	ICU	Interrupt Request Register 242	IR242	8	8	2 ICLK
0008 70F3h	ICU	Interrupt Request Register 243	IR243	8	8	2 ICLK
0008 70F4h	ICU	Interrupt Request Register 244	IR244	8	8	2 ICLK
0008 70F5h	ICU	Interrupt Request Register 245	IR245	8	8	2 ICLK
0008 70F6h	ICU	Interrupt Request Register 246	IR246	8	8	2 ICLK
0008 70F7h	ICU	Interrupt Request Register 247	IR247	8	8	2 ICLK
0008 70F8h	ICU	Interrupt Request Register 248	IR248	8	8	2 ICLK
0008 70F9h	ICU	Interrupt Request Register 249	IR249	8	8	2 ICLK
0008 711Bh	ICU	DTC Activation Enable Register 027	DTCER027	8	8	2 ICLK
0008 711Ch	ICU	DTC Activation Enable Register 028	DTCER028	8	8	2 ICLK
0008 711Dh	ICU	DTC Activation Enable Register 029	DTCER029	8	8	2 ICLK
0008 7124h	ICU	DTC Activation Enable Register 036	DTCER036	8	8	2 ICLK
0008 7125h	ICU	DTC Activation Enable Register 037	DTCER037	8	8	2 ICLK
0008 712Dh	ICU	DTC Activation Enable Register 045	DTCER045	8	8	2 ICLK
0008 712Eh	ICU	DTC Activation Enable Register 046	DTCER046	8	8	2 ICLK
0008 7140h	ICU	DTC Activation Enable Register 064	DTCER064	8	8	2 ICLK
0008 7141h	ICU	DTC Activation Enable Register 065	DTCER065	8	8	2 ICLK
0008 7142h	ICU	DTC Activation Enable Register 066	DTCER066	8	8	2 ICLK
0008 7143h	ICU	DTC Activation Enable Register 067	DTCER067	8	8	2 ICLK
0008 7144h	ICU	DTC Activation Enable Register 068	DTCER068	8	8	2 ICLK
0008 7145h	ICU	DTC Activation Enable Register 069	DTCER069	8	8	2 ICLK
0008 7146h	ICU	DTC Activation Enable Register 070	DTCER070	8	8	2 ICLK
0008 7147h	ICU	DTC Activation Enable Register 071	DTCER071	8	8	2 ICLK
0008 7166h	ICU	DTC Activation Enable Register 102	DTCER102	8	8	2 ICLK
0008 7167h	ICU	DTC Activation Enable Register 103	DTCER103	8	8	2 ICLK
0008 716Ah	ICU	DTC Activation Enable Register 106	DTCER106	8	8	2 ICLK
0008 7172h	ICU	DTC Activation Enable Register 114	DTCER114	8	8	2 ICLK
0008 7173h	ICU	DTC Activation Enable Register 115	DTCER115	8	8	2 ICLK
0008 7174h	ICU	DTC Activation Enable Register 116	DTCER116	8	8	2 ICLK
0008 7175h	ICU	DTC Activation Enable Register 117	DTCER117	8	8	2 ICLK
0008 7179h	ICU	DTC Activation Enable Register 121	DTCER121	8	8	2 ICLK
0008 717Ah	ICU	DTC Activation Enable Register 122	DTCER122	8	8	2 ICLK
0008 717Dh	ICU	DTC Activation Enable Register 125	DTCER125	8	8	2 ICLK
0008 717Eh	ICU	DTC Activation Enable Register 126	DTCER126	8	8	2 ICLK
0008 7181h	ICU	DTC Activation Enable Register 129	DTCER129	8	8	2 ICLK
0008 7182h	ICU	DTC Activation Enable Register 130	DTCER130	8	8	2 ICLK
0008 7183h	ICU	DTC Activation Enable Register 131	DTCER131	8	8	2 ICLK
0008 7184h	ICU	DTC Activation Enable Register 132	DTCER132	8	8	2 ICLK
0008 7186h	ICU	DTC Activation Enable Register 134	DTCER134	8	8	2 ICLK

Table 4.1 List of I/O Registers (Address Order) (11/16)

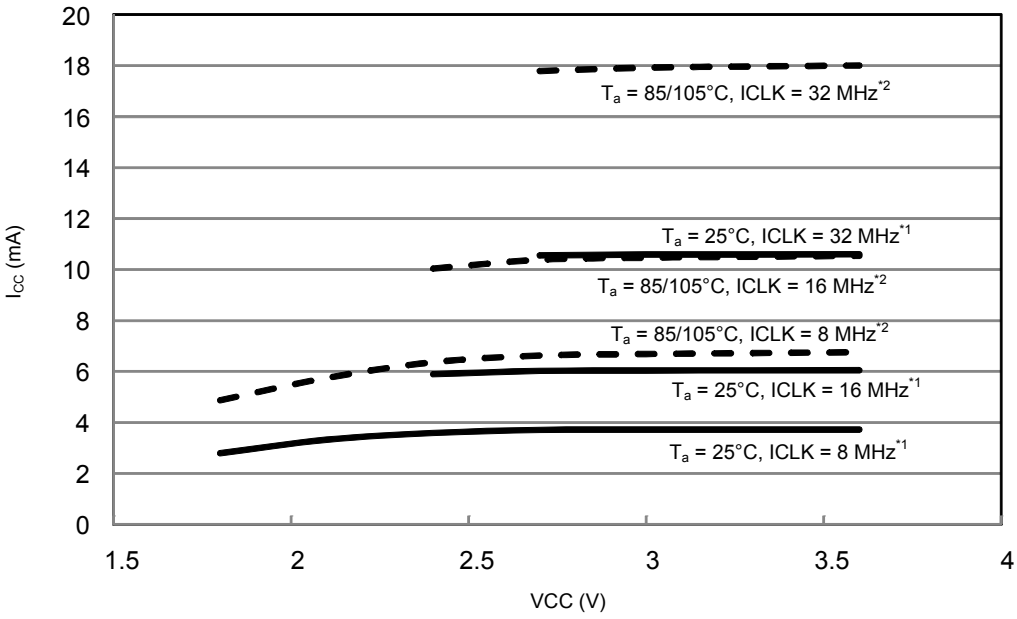
Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 B127h	ELC	Port Buffer Register 1	PDBF1	8	8	2 or 3 PCLKB
0008 B129h	ELC	Event Link Port Setting Register 0	PEL0	8	8	2 or 3 PCLKB
0008 B12Ah	ELC	Event Link Port Setting Register 1	PEL1	8	8	2 or 3 PCLKB
0008 B12Dh	ELC	Event Link Software Event Generation Register	ELSEGR	8	8	2 or 3 PCLKB
0008 B300h	SCI12	Serial Mode Register	SMR	8	8	2 or 3 PCLKB
0008 B301h	SCI12	Bit Rate Register	BRR	8	8	2 or 3 PCLKB
0008 B302h	SCI12	Serial Control Register	SCR	8	8	2 or 3 PCLKB
0008 B303h	SCI12	Transmit Data Register	TDR	8	8	2 or 3 PCLKB
0008 B304h	SCI12	Serial Status Register	SSR	8	8	2 or 3 PCLKB
0008 B305h	SCI12	Receive Data Register	RDR	8	8	2 or 3 PCLKB
0008 B306h	SCI12	Smart Card Mode Register	SCMR	8	8	2 or 3 PCLKB
0008 B307h	SCI12	Serial Extended Mode Register	SEMR	8	8	2 or 3 PCLKB
0008 B308h	SCI12	Noise Filter Setting Register	SNFR	8	8	2 or 3 PCLKB
0008 B309h	SCI12	I^2C Mode Register 1	SIMR1	8	8	2 or 3 PCLKB
0008 B30Ah	SCI12	I^2C Mode Register 2	SIMR2	8	8	2 or 3 PCLKB
0008 B30Bh	SCI12	I^2C Mode Register 3	SIMR3	8	8	2 or 3 PCLKB
0008 B30Ch	SCI12	I^2C Status Register	SISR	8	8	2 or 3 PCLKB
0008 B30Dh	SCI12	SPI Mode Register	SPMR	8	8	2 or 3 PCLKB
0008 B320h	SCI12	Extended Serial Mode Enable Register	ESMER	8	8	2 or 3 PCLKB
0008 B321h	SCI12	Control Register 0	CR0	8	8	2 or 3 PCLKB
0008 B322h	SCI12	Control Register 1	CR1	8	8	2 or 3 PCLKB
0008 B323h	SCI12	Control Register 2	CR2	8	8	2 or 3 PCLKB
0008 B324h	SCI12	Control Register 3	CR3	8	8	2 or 3 PCLKB
0008 B325h	SCI12	Port Control Register	PCR	8	8	2 or 3 PCLKB
0008 B326h	SCI12	Interrupt Control Register	ICR	8	8	2 or 3 PCLKB
0008 B327h	SCI12	Status Register	STR	8	8	2 or 3 PCLKB
0008 B328h	SCI12	Status Clear Register	STCR	8	8	2 or 3 PCLKB
0008 B329h	SCI12	Control Field 0 Data Register	CF0DR	8	8	2 or 3 PCLKB
0008 B32Ah	SCI12	Control Field 0 Compare Enable Register	CF0CR	8	8	2 or 3 PCLKB
0008 B32Bh	SCI12	Control Field 0 Receive Data Register	CF0RR	8	8	2 or 3 PCLKB
0008 B32Ch	SCI12	Primary Control Field 1 Data Register	PCF1DR	8	8	2 or 3 PCLKB
0008 B32Dh	SCI12	Secondary Control Field 1 Data Register	SCF1DR	8	8	2 or 3 PCLKB
0008 B32Eh	SCI12	Control Field 1 Compare Enable Register	CF1CR	8	8	2 or 3 PCLKB
0008 B32Fh	SCI12	Control Field 1 Receive Data Register	CF1RR	8	8	2 or 3 PCLKB
0008 B330h	SCI12	Timer Control Register	TCR	8	8	2 or 3 PCLKB
0008 B331h	SCI12	Timer Mode Register	TMR	8	8	2 or 3 PCLKB
0008 B332h	SCI12	Timer Prescaler Register	TPRE	8	8	2 or 3 PCLKB
0008 B333h	SCI12	Timer Count Register	TCNT	8	8	2 or 3 PCLKB
0008 C000h	PORT0	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C001h	PORT1	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C002h	PORT2	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C003h	PORT3	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C004h	PORT4	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C005h	PORT5	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Ah	PORTA	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Bh	PORTB	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Ch	PORTC	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Eh	PORTE	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C012h	PORTJ	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C020h	PORT0	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C021h	PORT1	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C022h	PORT2	Port Output Data Register	PODR	8	8	2 or 3 PCLKB

[128-Kbyte or less flash memory]

Table 5.7 DC Characteristics (5) (1/2)

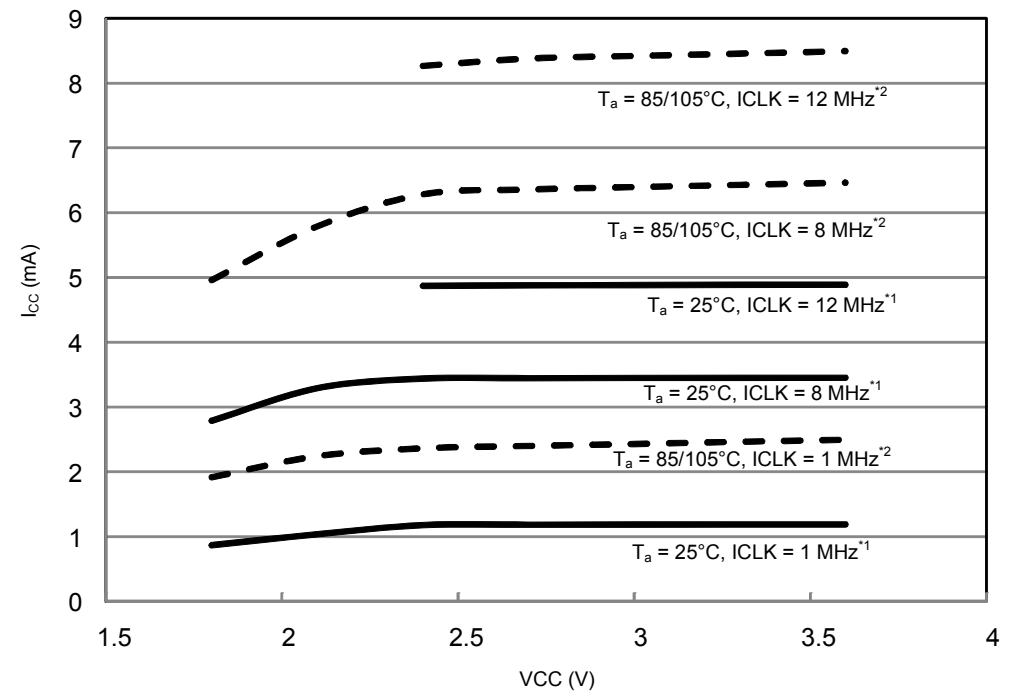
Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item					Symbol	Typ *4	Max	Unit	Test Conditions
Supply current*1	High-speed operating mode	Normal operating mode	No peripheral operation*2	ICLK = 32 MHz	I_{CC}	3.2	—	mA	
				ICLK = 16 MHz		2.2	—		
				ICLK = 8 MHz		1.7	—		
			All peripheral operation: Normal*3	ICLK = 32 MHz		10.6	—		
				ICLK = 16 MHz		6.1	—		
				ICLK = 8 MHz		3.7	—		
			All peripheral operation: Max.*3	ICLK = 32 MHz		—	24		
		Sleep mode	No peripheral operation*2	ICLK = 32 MHz		1.8	—		
				ICLK = 16 MHz		1.4	—		
				ICLK = 8 MHz		1.1	—		
			All peripheral operation: Normal*3	ICLK = 32 MHz		6.4	—		
				ICLK = 16 MHz		3.7	—		
				ICLK = 8 MHz		2.4	—		
		Deep sleep mode	No peripheral operation*2	ICLK = 32 MHz		1.2	—		
				ICLK = 16 MHz		1.0	—		
				ICLK = 8 MHz		0.90	—		
			All peripheral operation: Normal*3	ICLK = 32 MHz		4.6	—		
				ICLK = 16 MHz		2.8	—		
				ICLK = 8 MHz		1.8	—		
		Increase during flash rewrite*5				2.5	—		
	Middle-speed operating modes	Normal operating mode	No peripheral operation*6	ICLK = 12 MHz	I_{CC}	2.0	—	mA	
				ICLK = 8 MHz		1.3	—		
				ICLK = 1 MHz		0.75	—		
			All peripheral operation: Normal*7	ICLK = 12 MHz		4.9	—		
				ICLK = 8 MHz		3.5	—		
				ICLK = 1 MHz		1.2	—		
			All peripheral operation: Max.*7	ICLK = 12 MHz		—	11		
		Sleep mode	No peripheral operation*6	ICLK = 12 MHz		1.4	—		
				ICLK = 8 MHz		0.85	—		
				ICLK = 1 MHz		0.65	—		
			All peripheral operation: Normal*7	ICLK = 12 MHz		3.2	—		
				ICLK = 8 MHz		2.2	—		
				ICLK = 1 MHz		1.0	—		
		Deep sleep mode	No peripheral operation*6	ICLK = 12 MHz		1.2	—		
				ICLK = 8 MHz		0.70	—		
				ICLK = 1 MHz		0.60	—		
			All peripheral operation: Normal*7	ICLK = 12 MHz		2.5	—		
				ICLK = 8 MHz		1.8	—		
				ICLK = 1 MHz		0.90	—		
		Increase during flash rewrite*5				2.5	—		



Note 1. All peripheral operation is normal. This does not include BGO operation.
Average value of the tested middle samples during product evaluation.
Note 2. All peripheral operation is maximum. This does not include BGO operation.
Average value of the tested upper-limit samples during product evaluation.

Figure 5.1 Voltage Dependency in High-Speed Operating Mode (Reference Data)



Note 1. All peripheral operation is normal. This does not include BGO operation.
Average value of the tested middle samples during product evaluation.
Note 2. All peripheral operation is maximum. This does not include BGO operation.
Average value of the tested upper-limit samples during product evaluation.

Figure 5.2 Voltage Dependency in Middle-Speed Operating Mode (Reference Data)

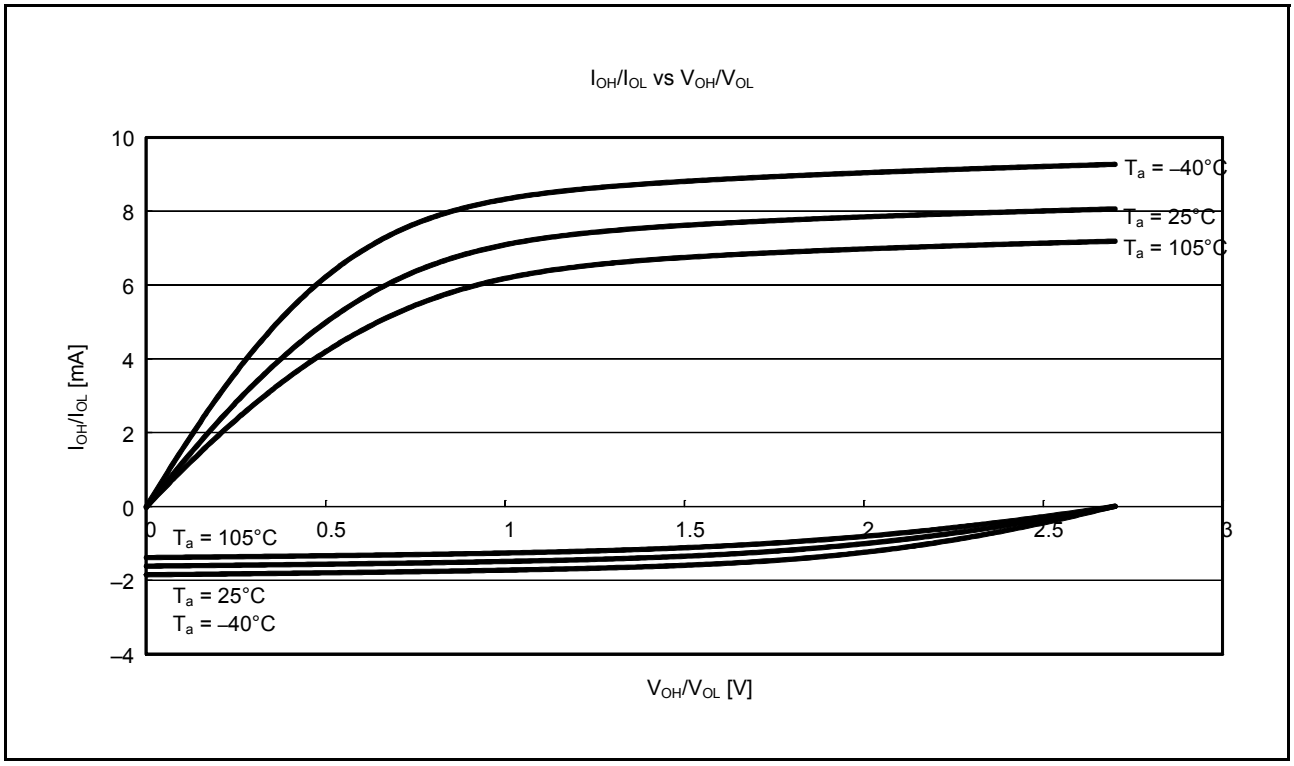


Figure 5.21 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics of Ports P40 to P44, P46, Ports PJ6, PJ7 at VCC = 2.7 V (Reference Data)

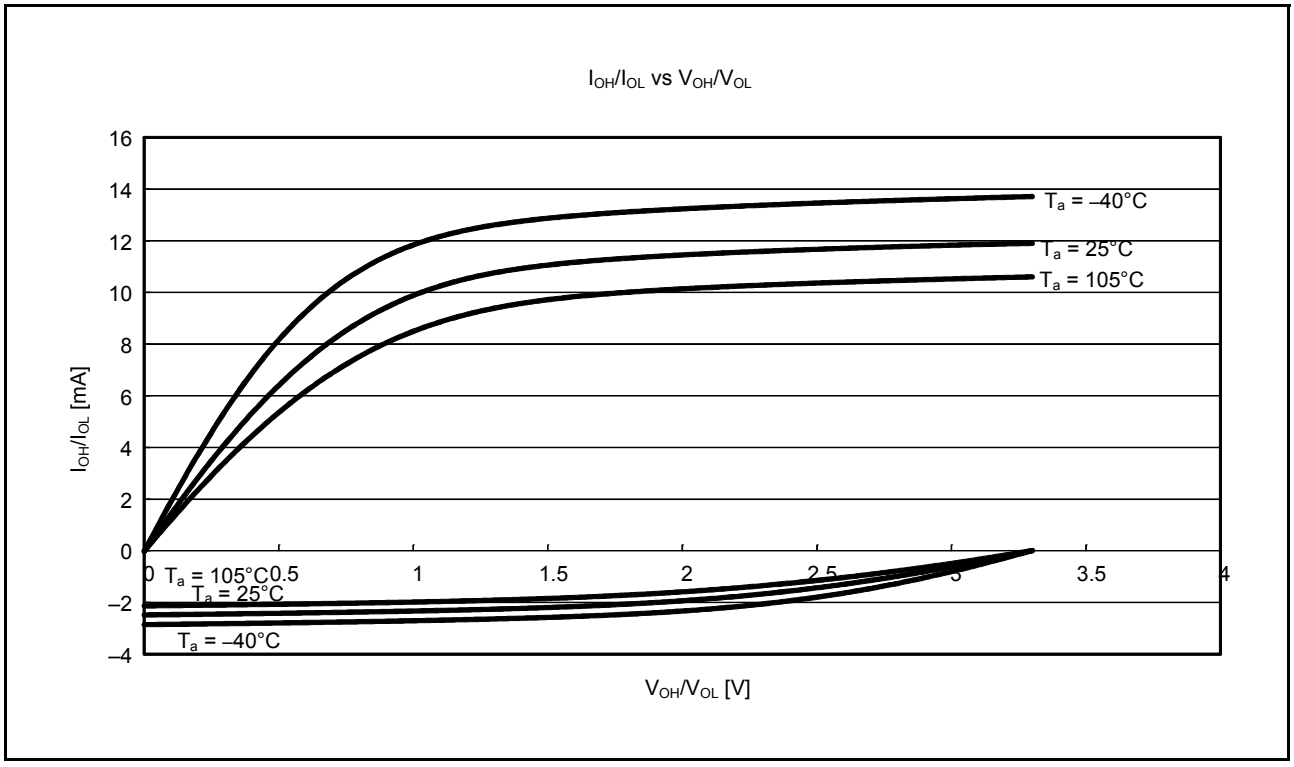


Figure 5.22 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics of Ports P40 to P44, P46, Ports PJ6, PJ7 at VCC = 3.3 V (Reference Data)

5.3 AC Characteristics

5.3.1 Clock Timing

Table 5.21 Operation Frequency Value (High-Speed Operating Mode)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	VCC				Unit
			1.8 to 2.4 V	2.4 to 2.7 V	2.7 to 3.6 V	When USB in Use*4	
Maximum operating frequency	System clock (ICLK)	f_{max}	8	16	32	24	MHz
	FlashIF clock (FCLK)*1, *2		8	16	32	24	
	Peripheral module clock (PCLKB)		8	16	32	24	
	Peripheral module clock (PCLKD)*3		8	16	32	24	
	USB clock (UCLK)	f_{usb}	—	—	—	48	

Note 1. The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note 2. The frequency accuracy of FCLK should be ±3.5%. Confirm the frequency accuracy of the clock source.
Note 3. The lower-limit frequency of PCLKD is 4 MHz at 2.4 V or above and 1 MHz at below 2.4 V when the A/D converter is in use.
Note 4. The VCC_USB range is 3.0 to 3.6 V when the USB clock is in use.

Table 5.22 Operation Frequency Value (Middle-Speed Operating Mode)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	VCC				Unit
			1.8 to 2.4 V	2.4 to 2.7 V	2.7 to 3.6 V	When USB in Use*4	
Maximum operating frequency	System clock (ICLK)	f_{max}	8	12	12	12	MHz
	FlashIF clock (FCLK)*1, *2		8	12	12	12	
	Peripheral module clock (PCLKB)		8	12	12	12	
	Peripheral module clock (PCLKD)*3		8	12	12	12	
	USB clock (UCLK)	f_{usb}	—	—	—	48	

Note 1. The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note 2. The frequency accuracy of FCLK should be ±3.5%.
Note 3. The lower-limit frequency of PCLKD is 4 MHz at 2.4 V or above and 1 MHz at below 2.4 V when the A/D converter is in use.
Note 4. The VCC_USB range is 3.0 to 3.6 V when the USB clock is in use.

Table 5.23 Operation Frequency Value (Low-Speed Operating Mode)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	VCC			Unit
			1.8 to 2.4 V	2.4 to 2.7 V	2.7 to 3.6 V	
Maximum operating frequency	System clock (ICLK)	f_{max}	32.768			kHz
	FlashIF clock (FCLK)*1		32.768			
	Peripheral module clock (PCLKB)		32.768			
	Peripheral module clock (PCLKD)*2		32.768			

Note 1. Programming and erasing the flash memory is impossible.
Note 2. The A/D converter cannot be used.

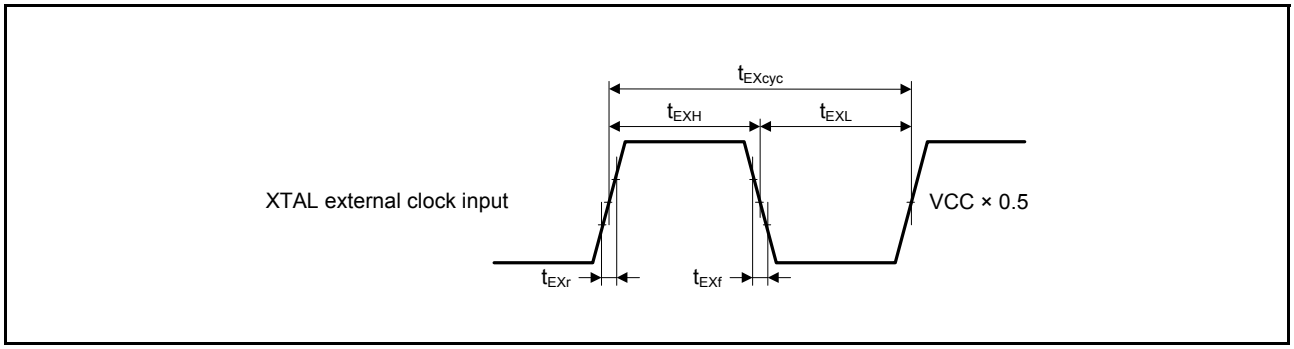


Figure 5.23 XTAL External Clock Input Timing

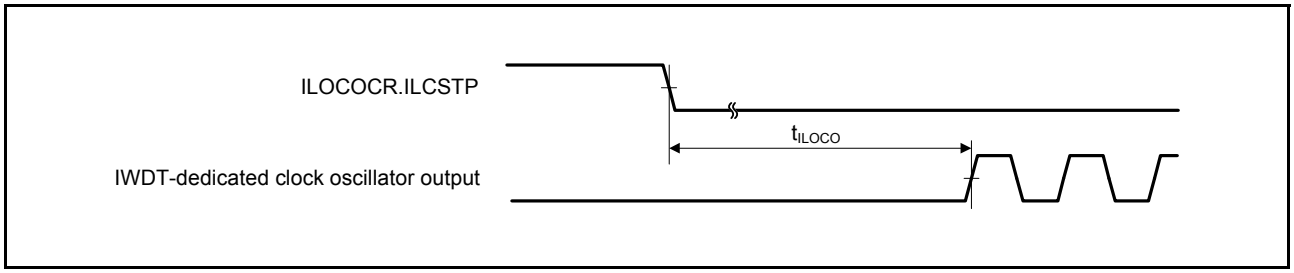


Figure 5.24 IWDT-Dedicated Clock Oscillation Start Timing

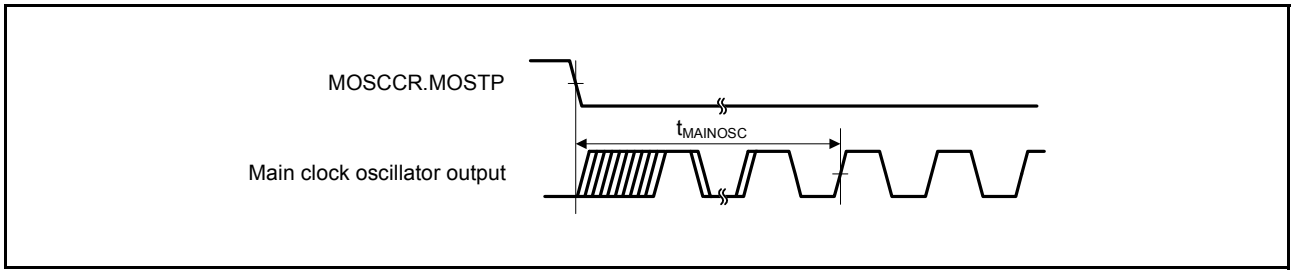


Figure 5.25 Main Clock Oscillation Start Timing

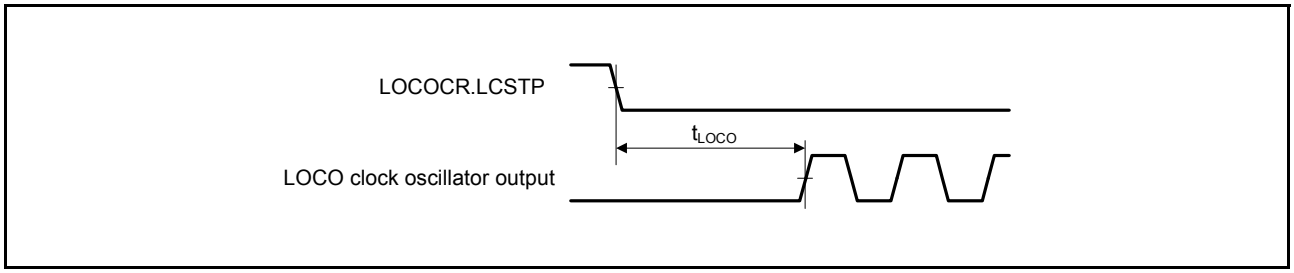


Figure 5.26 LOCO Clock Oscillation Start Timing

5.3.2 Reset Timing

Table 5.25 Reset Timing

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
RES# pulse width	At power-on	t_{RESWP}	3	—	—	ms	Figure 5.31
	Other than above	t_{RESW}	30	—	—	µs	Figure 5.32
Wait time after RES# cancellation (at power-on)	At normal startup*1	t_{RESWT}	—	8.5	—	ms	Figure 5.31
	During fast startup time*2	t_{RESWT}	—	560	—	µs	
Wait time after RES# cancellation (during powered-on state)		t_{RESWT}	—	114	—	µs	Figure 5.32
Independent watchdog timer reset period		t_{RESWIW}	—	1	—	IWDT clock cycle	Figure 5.33
Software reset period		t_{RESWSW}	—	1	—	ICLK cycle	
Wait time after independent watchdog timer reset cancellation*3		t_{RESW2}	—	300	—	µs	
Wait time after software reset cancellation		t_{RESW2}	—	168	—	µs	

Note 1. When OFS1.(STUPLVD1REN, FASTSTUP) = 11b.
Note 2. When OFS1.(STUPLVD1REN, FASTSTUP) ≠ 11b.
Note 3. When IWDTCR.CKS[3:0] = 0000b.

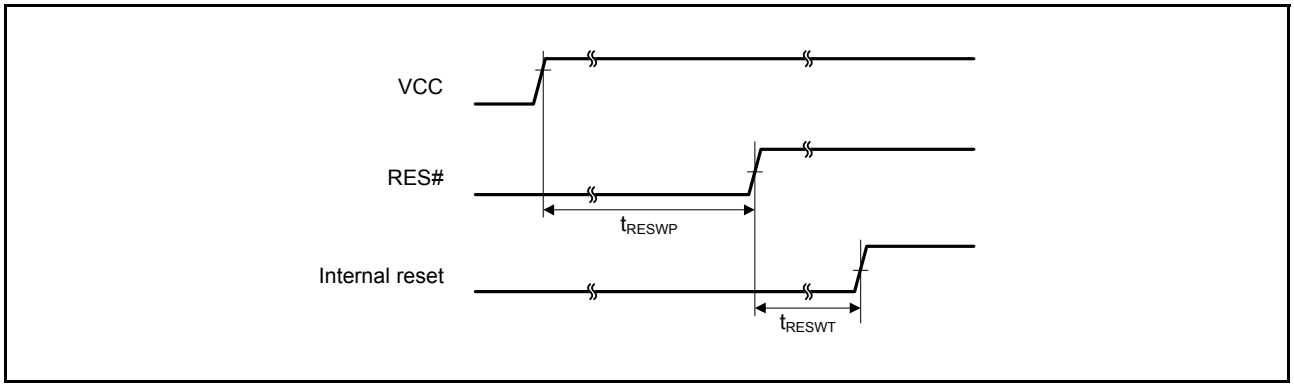


Figure 5.31 Reset Input Timing at Power-On

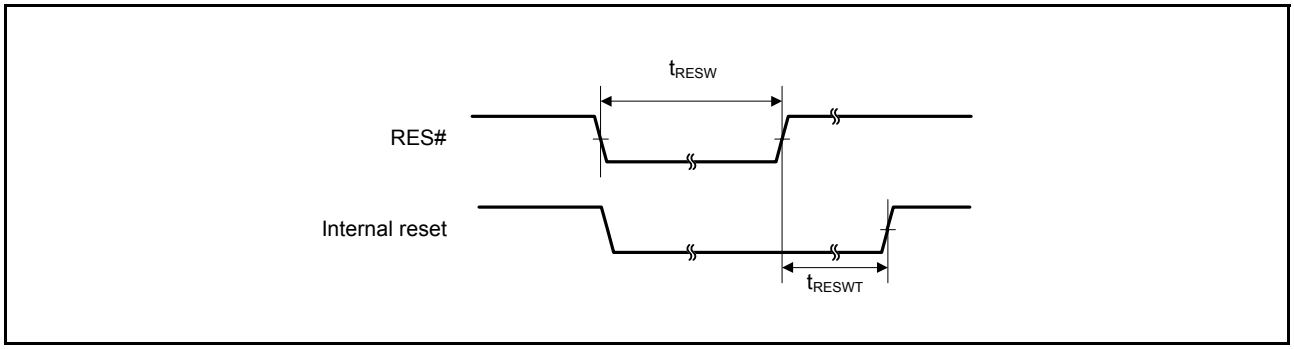


Figure 5.32 Reset Input Timing (1)

Table 5.36 Timing of On-Chip Peripheral Modules (5)

Conditions: 2.7 V ≤ VCC = VCC_USB ≤ 3.6 V, 2.7 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, fPCLKB ≤ 32 MHz, T_a = –40 to +105°C

Item		Symbol	Min.	Max.	Unit	Test Conditions
Simple I²C (Standard mode)	SDA0 input rise time	t_{Sr}	—	1000	ns	Figure 5.53
	SDA0 input fall time	t_{Sf}	—	300	ns	
	SDA0 input spike pulse removal time	t_{SP}	0	4 × t_{pcyc}*1	ns	
	Data input setup time	t_{SDAS}	250	—	ns	
	Data input hold time	t_{SDAH}	0	—	ns	
	SCL0, SDA0 capacitive load	C_b	—	400	pF	
Simple I²C (Fast mode)	SCL0, SDA0 input rise time	t_{Sr}	—	300	ns	Figure 5.53
	SCL0, SDA0 input fall time	t_{Sf}	—	300	ns	
	SCL0, SDA0 input spike pulse removal time	t_{SP}	0	4 × t_{pcyc}*1	ns	
	Data input setup time	t_{SDAS}	100	—	ns	
	Data input hold time	t_{SDAH}	0	—	ns	
	SCL0, SDA0 capacitive load	C_b	—	400	pF	

Note: • t_{Pcyc}: PCLK cycle

Note 1. This applies when the SMR.CKS[1:0] bits = 00b and the SNFR.NFCS[2:0] bits = 010b while the SNFR.NFE bit = 1 and the digital filter is enabled.

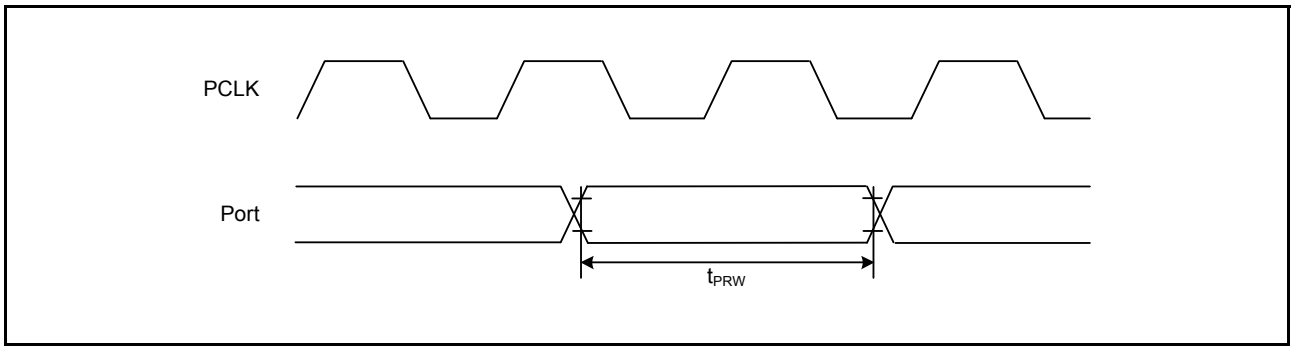


Figure 5.38 I/O Port Input Timing

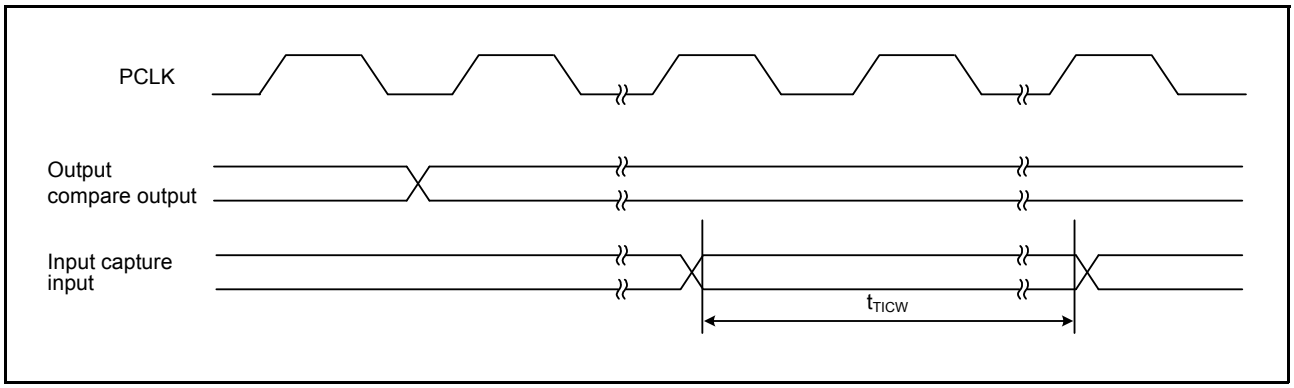


Figure 5.39 MTU2 Input/Output Timing

Table 5.41 A/D Converter Channel Classification

Classification	Channel	Conditions	Remarks
High-precision channel	AN000 to AN004, AN006	AVCC0 = 1.8 to 3.6 V	Pins AN000 to AN004 and AN006 cannot be used as digital outputs when the A/D converter is in use.
Normal-precision channel	AN008 to AN015		
Internal reference voltage input channel	Internal reference voltage	AVCC0 = 2.0 to 3.6 V	
Temperature sensor input channel	Temperature sensor output	AVCC0 = 2.0 to 3.6 V	

Table 5.42 A/D Internal Reference Voltage Characteristics

Conditions: 2.0 V ≤ VCC = VCC_USB ≤ 3.6 V, 2.0 V ≤ AVCC0 ≤ 3.6 V*1, VSS = AVSS0 = VREFL0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item	Min.	Typ.	Max.	Unit	Test Conditions
Internal reference voltage input channel*2	1.36	1.43	1.50	V	

Note 1. The internal reference voltage cannot be selected for input channels when AVCC0 < 2.0 V.
Note 2. The A/D internal reference voltage indicates the voltage when the internal reference voltage is input to the A/D converter.

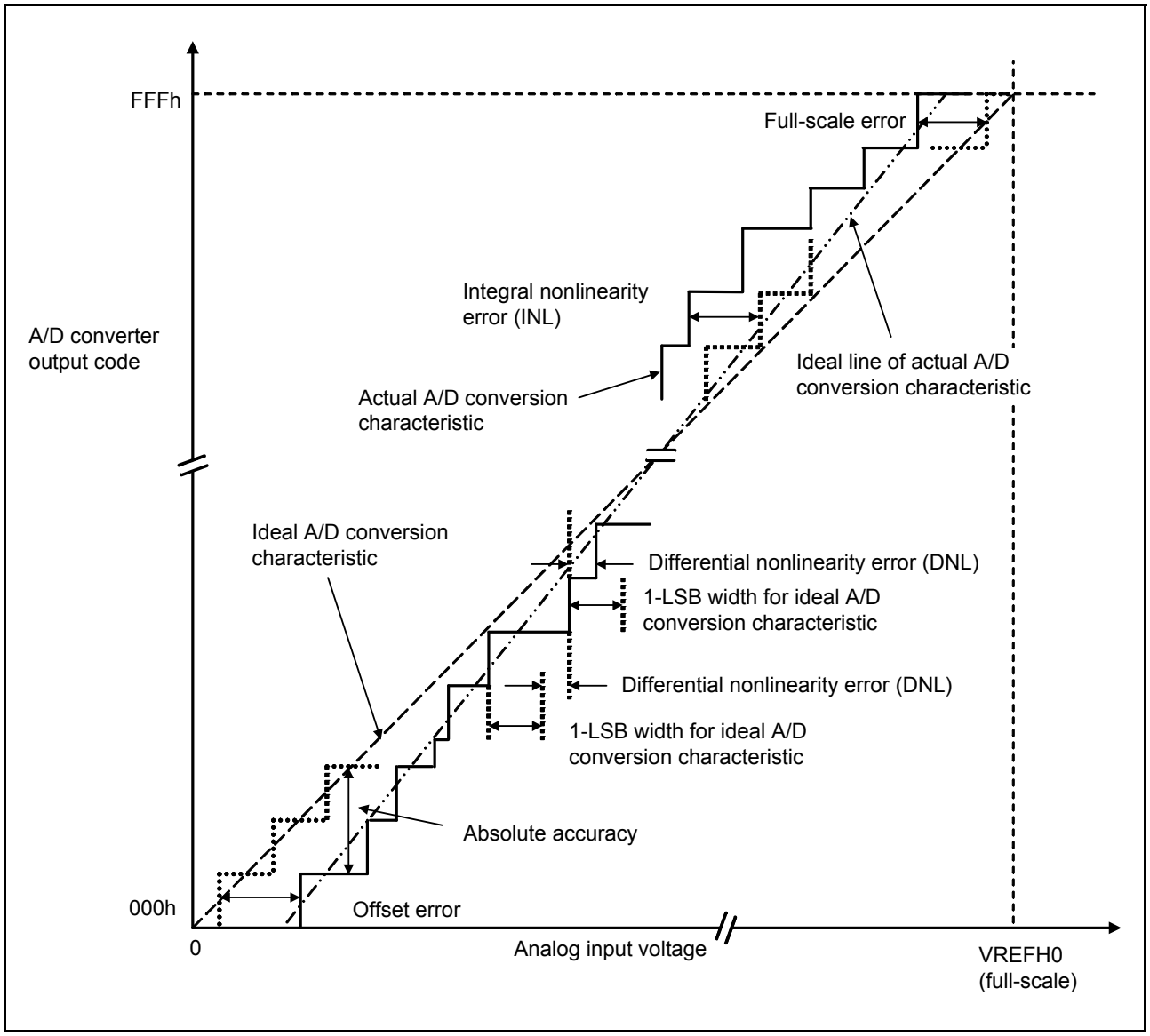


Figure 5.57 Illustration of A/D Converter Characteristic Terms

Absolute accuracy

Absolute accuracy is the difference between output code based on the theoretical A/D conversion characteristics, and the actual A/D conversion result. When measuring absolute accuracy, the voltage at the midpoint of the width of analog input voltage (1-LSB width), that can meet the expectation of outputting an equal code based on the theoretical A/D conversion characteristics, is used as an analog input voltage. For example, if 12-bit resolution is used and if reference voltage (VREFH0 = 3.072 V), then 1-LSB width becomes 0.75 mV, and 0 mV, 0.75 mV, 1.5 mV, ... are used as analog input voltages.

If analog input voltage is 6 mV, absolute accuracy = ±5 LSB means that the actual A/D conversion result is in the range of 003h to 00Dh though an output code, 008h, can be expected from the theoretical A/D conversion characteristics.

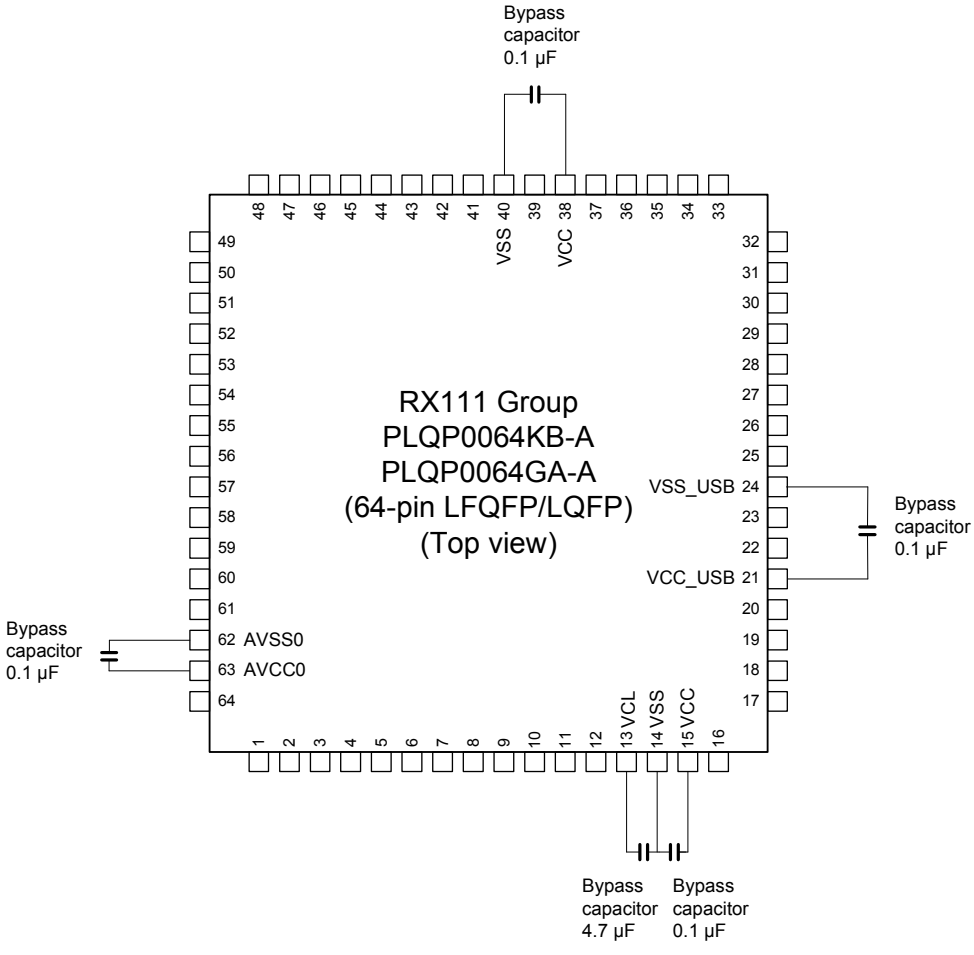
Integral nonlinearity error (INL)

Integral nonlinearity error is the maximum deviation between the ideal line when the measured offset and full-scale errors are zeroed, and the actual output code.

5.12 Usage Notes

5.12.1 Connecting VCL Capacitor and Bypass Capacitors

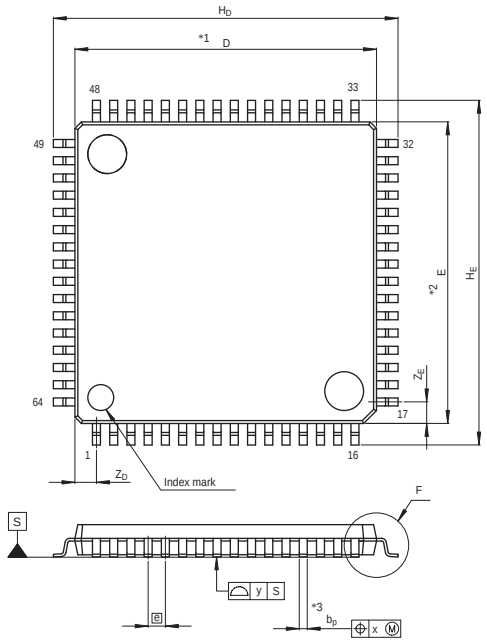
This MCU integrates an internal voltage-down circuit, which is used for lowering the power supply voltage in the internal MCU to adjust automatically to the optimum level. A 4.7-µF capacitor needs to be connected between this internal voltage-down power supply (VCL pin) and VSS pin. Figure 5.63 to Figure 5.64 shows how to connect external capacitors. Place an external capacitor close to the pins. Do not apply the power supply voltage to the VCL pin. Insert a multilayer ceramic capacitor as a bypass capacitor between each pair of the power supply pins. Implement a bypass capacitor to the MCU power supply pins as close as possible. Use a recommended value of 0.1 µF as the capacitance of the capacitors. For the capacitors related to crystal oscillation, see section 9, Clock Generation Circuit in the User's Manual: Hardware. For the capacitors related to analog modules, also see section 30, 12-Bit A/D Converter (S12ADb) in the User's Manual: Hardware.
For notes on designing the printed circuit board, see the descriptions of the application note "Hardware Design Guide" (R01AN1411EJ). The latest version can be downloaded from Renesas Electronics Website.

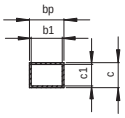


Note. Do not apply the power supply voltage to the VCL pin.
Use a 4.7-µF multilayer ceramic for the VCL pin and place it close to the pin.
A recommended value is shown for the capacitance of the bypass capacitors.

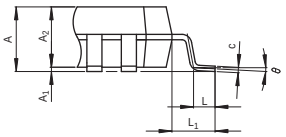
Figure 5.63 Connecting Capacitors (64 Pins)

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP64-14x14-0.80	PLQP0064GA-A	64P6U-A/ —	0.7g





Terminal cross section



Detail F

NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	13.9	14.0	14.1
E	13.9	14.0	14.1
A_2	—	1.4	—
H_D	15.8	16.0	16.2
H_E	15.8	16.0	16.2
A	—	—	1.7
A_1	0	0.1	0.2
b_p	0.32	0.37	0.42
b_1	—	0.35	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.8	—
x	—	—	0.20
y	—	—	0.10
Z_D	—	1.0	—
Z_E	—	1.0	—
L	0.3	0.5	0.7
L_1	—	1.0	—

Figure B 64-Pin LQFP (PLQP0064GA-A)

Classifications

- Items with Technical Update document number: Changes according to the corresponding issued Technical Update
- Items without Technical Update document number: Minor changes that do not require Technical Update to be issued

Rev.	Date	Description		Classification
		Page	Summary	
1.30	May 31, 2016	1. Overview		
		18 to 26	Table 1.5 to 1.9 Note 2 regarding I/O power source is AVCC0 for the ports (P4, PJ6, and PJ7), added	
		5. Electrical Characteristics		
		49	Table 5.1 Absolute Maximum Ratings, Analog power supply voltage added	
		49	Table 5.2 Recommended Operating Conditions, VREFH0 / VREFL0 added	
		58	Figure 5.4 Voltage Dependency in High-Speed Operating Mode (Reference Data) added	
		59	Figure 5.5 Voltage Dependency in Middle-Speed Operating Mode (Reference Data) added	
		59	Figure 5.6 Voltage Dependency in Low-Speed Operating Mode (Reference Data) added	
		60	Table 5.9 DC Characteristics (7), Increment for IWDT operation added	
		62	Table 5.10 DC Characteristics (8), Increment for IWDT operation added	
		62	Figure 5.9 Voltage Dependency in Software Standby Mode (Reference Data) added	
		63	Figure 5.10 Temperature Dependency in Software Standby Mode (Reference Data) added	
		63	Table 5.11 DC Characteristics (9) added	TN-RX*-A134A/E
		64	Table 5.12 DC Characteristics (10), LDV1, 2 added	
		66, 67	Table 5.18 Permissible Output Currents is divided into D version and G version	TN-RX*-A134A/E
		110	Table 5.49 ROM (Flash Memory for Code Storage) Characteristics (2), Erasure time - 256-Kbyte added	TN-RX*-A132A/E
		111	Table 5.50 ROM (Flash Memory for Code Storage) Characteristics (3), Temperature range for the programming/erasure operation changed and Erasure time - 256-Kbyte added	TN-RX*-A132A/E
		112	Table 5.52 E2 DataFlash Characteristics (2), Low speed FCLK changed and Erasure time - 8-Kbyte added	TN-RX*-A132A/E
		112	Table 5.53 E2 DataFlash Characteristics (3), Temperature range for the programming/erasure operation changed, Low speed FCLK changed and Erasure time - 8-Kbyte added	TN-RX*-A132A/E
		113, 114	5.12 Usage Notes added	

NOTES FOR CMOS DEVICES

(1) VOLTAGE APPLICATION WAVEFORM AT INPUT PIN: Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between VIL (MAX) and VIH (MIN) due to noise, etc., the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between VIL (MAX) and VIH (MIN).

(2) HANDLING OF UNUSED INPUT PINS: Unconnected CMOS device inputs can be cause of malfunction. If an input pin is unconnected, it is possible that an internal input level may be generated due to noise, etc., causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using pull-up or pull-down circuitry. Each unused pin should be connected to VDD or GND via a resistor if there is a possibility that it will be an output pin. All handling related to unused pins must be judged separately for each device and according to related specifications governing the device.

(3) PRECAUTION AGAINST ESD: A strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it when it has occurred. Environmental control must be adequate. When it is dry, a humidifier should be used. It is recommended to avoid using insulators that easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors should be grounded. The operator should be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with mounted semiconductor devices.

(4) STATUS BEFORE INITIALIZATION: Power-on does not necessarily define the initial status of a MOS device. Immediately after the power source is turned ON, devices with reset functions have not yet been initialized. Hence, power-on does not guarantee output pin levels, I/O settings or contents of registers. A device is not initialized until the reset signal is received. A reset operation must be executed immediately after power-on for devices with reset functions.

(5) POWER ON/OFF SEQUENCE: In the case of a device that uses different power supplies for the internal operation and external interface, as a rule, switch on the external power supply after switching on the internal power supply. When switching the power supply off, as a rule, switch off the external power supply and then the internal power supply. Use of the reverse power on/off sequences may result in the application of an overvoltage to the internal elements of the device, causing malfunction and degradation of internal elements due to the passage of an abnormal current. The correct power on/off sequence must be judged separately for each device and according to related specifications governing the device.

(6) INPUT OF SIGNAL DURING POWER OFF STATE : Do not input signals or an I/O pull-up power supply while the device is not powered. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Input of signals during the power off state must be judged separately for each device and according to related specifications governing the device.